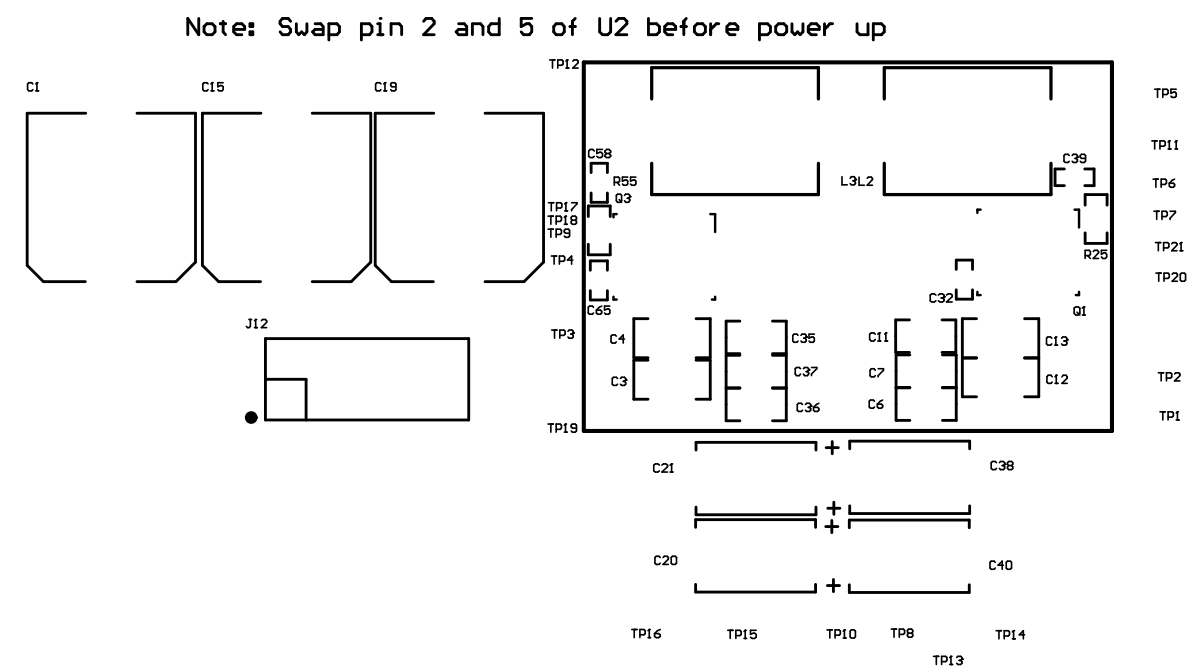
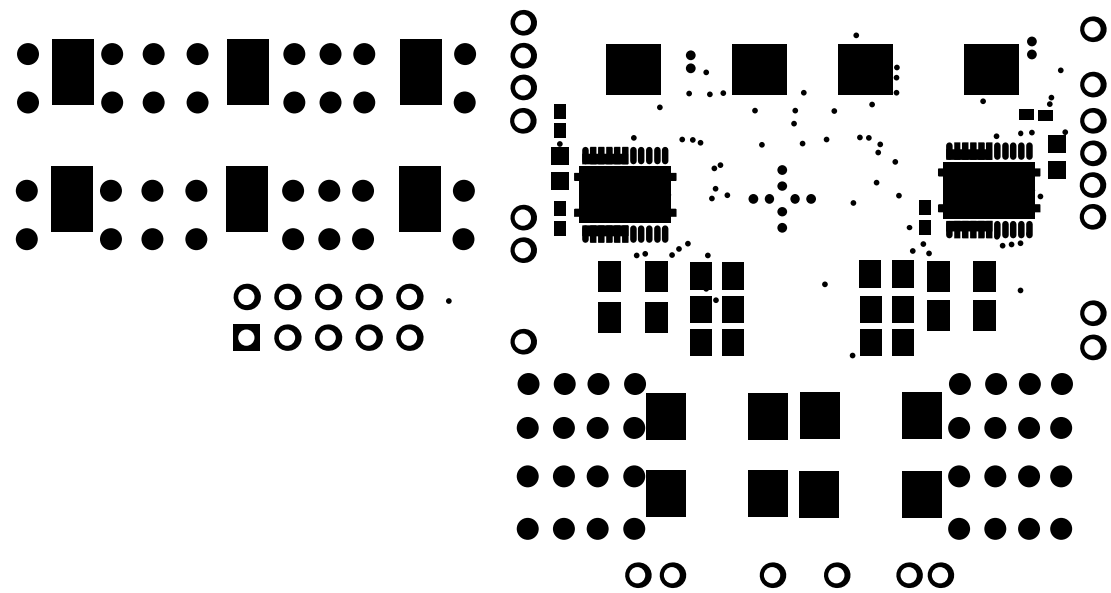




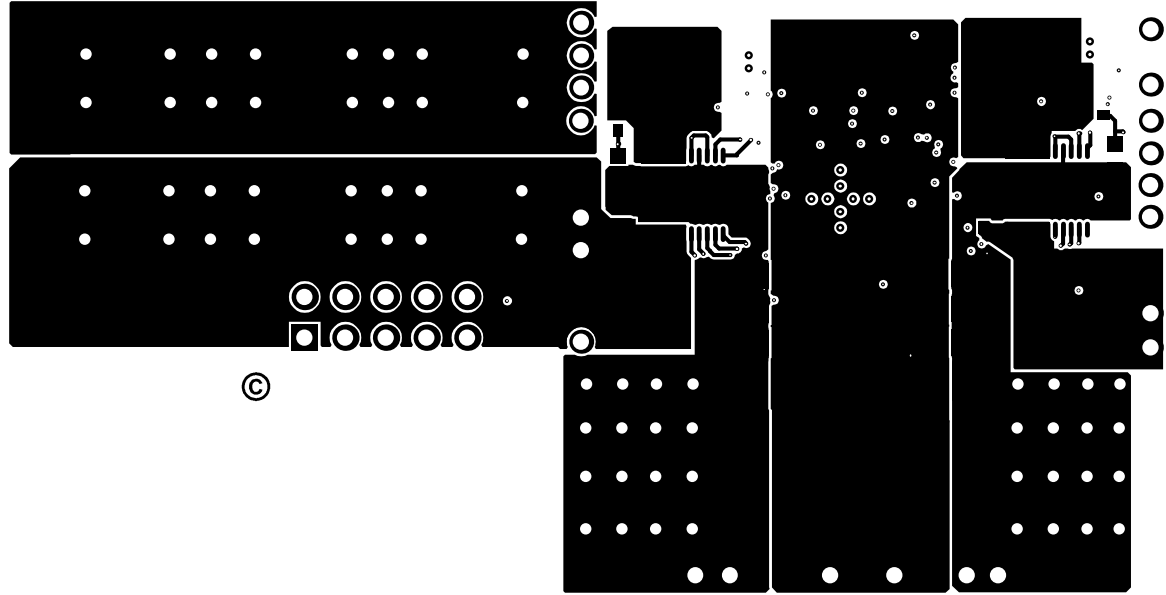
ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP4482		
PLOT NAME = Top Overlay	GENERATED : 4/1/2016 6:05:51 PM	TEXAS INSTRUMENTS	



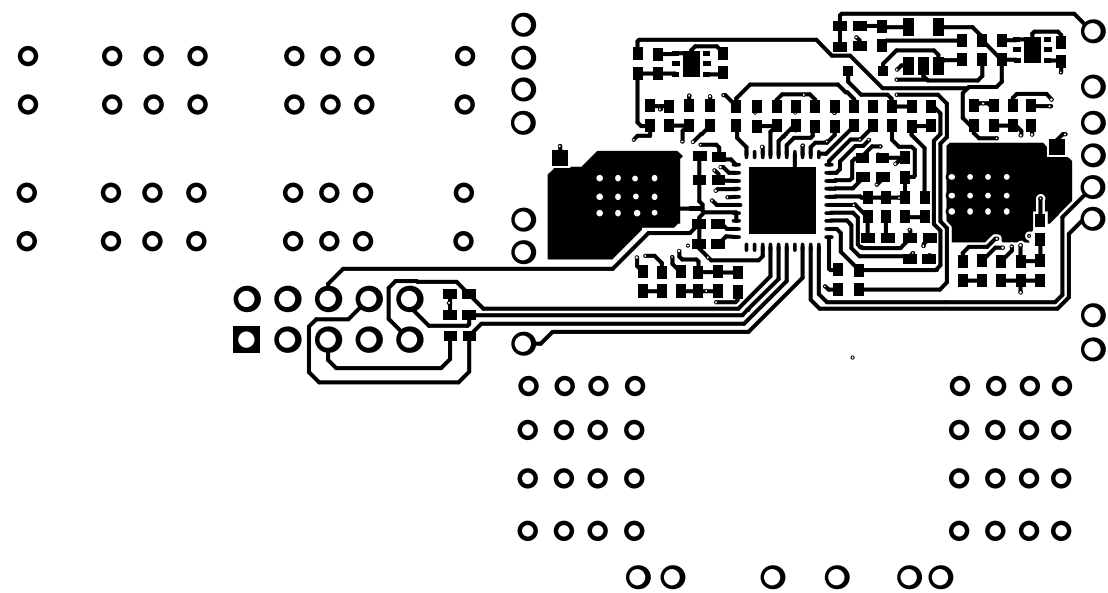
ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP4482		
PLOT NAME = Top Solder Mask	GENERATED : 4/1/2016	6:05:53 PM	TEXAS INSTRUMENTS



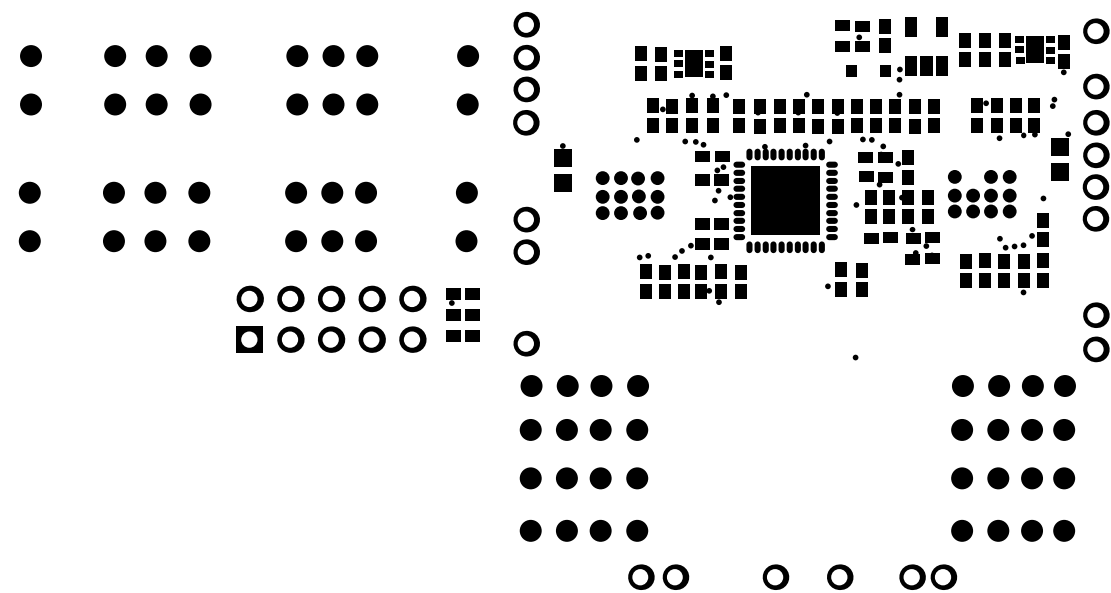
ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
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PLOT NAME = Top Layer	GENERATED : 4/1/2016	6:05:54 PM	TEXAS INSTRUMENTS



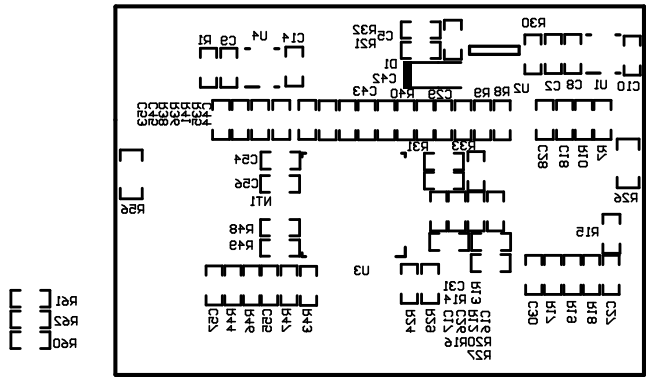
ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP4482		
PLOT NAME = Bottom Layer	GENERATED : 4/1/2016	6:05:55 PM	TEXAS INSTRUMENTS



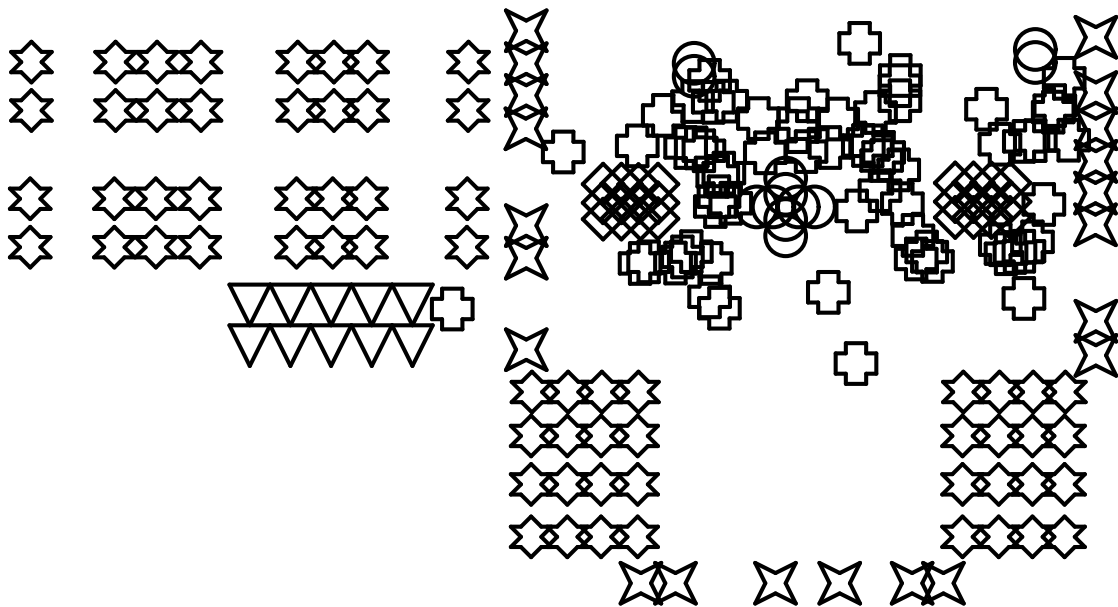
ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP4482		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/1/2016	6:05:56 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP4482		
PLOT NAME = Bottom Overlay	GENERATED : 4/1/2016 6:05:58 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊕	66	5.00mil (0.127mm)	PTH	Round
○	12	7.87mil (0.200mm)	PTH	Round
◇	24	15.00mil (0.381mm)	PTH	Round
✱	64	28.00mil (0.711mm)	PTH	Round
✂	21	39.37mil (1.000mm)	PTH	Round
▽	10	40.00mil (1.016mm)	PTH	Round
	197 Total			

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP4482		
PLOT NAME = Drill Drawing	GENERATED : 4/1/2016 6:05:59 PM		TEXAS INSTRUMENTS

ALL ARTWORK VIEWED FROM TOP SIDE

	PMP4482	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP4482		
PLOT NAME = Board Dimensions	GENERATED : 4/1/2016 6:06:01 PM		TEXAS INSTRUMENTS

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